



From Core Wars Intel/AMD to Seagate Storage Revolution

#ITguide

#NVIDIAGuide

#LENOVOguide

Agenda



CPU Intel

Xeon 6 and Xeon 6+ Overview



CPU AMD

EPYC 5th Gen and Preparation for 6th Gen



Seagate Mozaic

HAMR at Scale

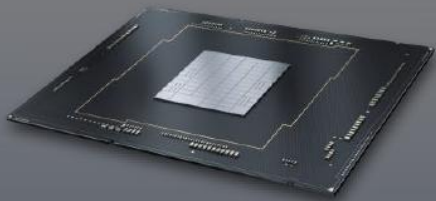


DRAM Market Analysis

Kingston's Strategy and Pricing Trends

Intel's Disaggregation Journey

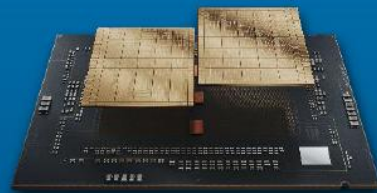
Intel Xeon 3rd Gen
Ice Lake



Monolithic

10nm

Intel Xeon 4th & 5th Gen
Sapphire & Emerald Rapids



Tiles with I/O mem & compute

EMIB

intel
7

Intel Xeon 6
Granite Rapid & Sierra Forest



I/O tiles

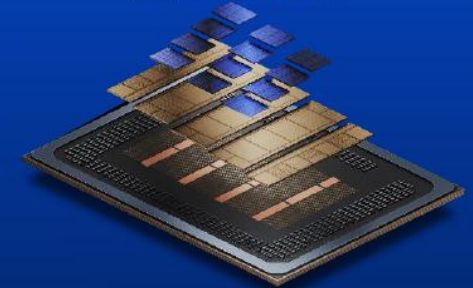
Compute tiles (E-core & P-core)

EMIB

intel
7

intel
3

Intel Xeon 6+
Clearwater Forest



I/O tiles

Base tiles

Compute tiles

EMIB

Foveros Direct 3D

intel
7

intel
3

intel
18A

Intel Xeon Processors are Designed to Meet Market Needs

The best processors to meet diverse performance and efficiency requirements

P-core Per-core performance

for compute-intensive workloads

Intel® Xeon® 6

Previously codenamed
Granite Rapids



6900P Series • LGA 7529

Up to 128 cores / 256 threads
12-ch DDR5 | MCR DIMM 8800 MT/s
96× PCIe 5.0 | TDP: up to 500 W

6700P / 6500P Series • LGA 4710

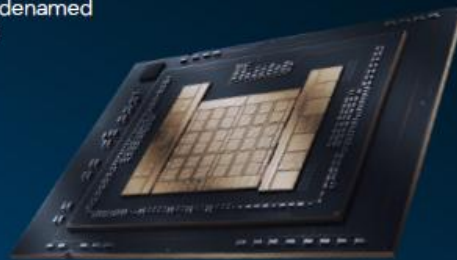
Up to 86 cores / 172 threads
8-ch DDR5 | RDIMM/MCR DIMM
96× PCIe 5.0 | TDP: up to 350 W

E-core Performance per watt

for high-density compute and
scale-out workloads

Intel® Xeon® 6

Previously codenamed
Sierra Forest



6900E Series • LGA 7529

Up to 288 cores / 288 threads
12-ch DDR5 | RDIMM 6400 MT/s
96× PCIe 5.0 | TDP: up to 500 W

6700E / 6500E Series • LGA 4710

Up to 144 cores / 144 threads
8-ch DDR5 | RDIMM 6400 MT/s
88× PCIe 5.0 | TDP: up to 250 W

Introducing Intel® Xeon® 6+

First 18A CPU in the data center

P-core Per-core performance

for compute-intensive workloads

Intel® Xeon® 6

Previously codenamed
Granite Rapids



E-Cores • Clearwater Forest

Up to 288 Darkmont E-cores
12-ch DDR5-8000 | 576 MB LLC
96× PCIe 5.0 | TDP: 300–500 W

Intel 18A process | Foveros Direct 3D
12 compute tiles | Glass Core substrate
17% IPC uplift vs Sierra Forest

E-core Performance per watt

for high-density compute and
scale-out workloads

Intel® Xeon® 6

Previously codenamed
Sierra Forest



Intel® Xeon® 6+

Previously codenamed
Clearwater Forest



Multiplexed Rank DIMM (MRDIMM)

Granite Rapids-SP/AP

Clearwater Forest-AP

~~Multiplexed Combined Rank DIMM (MCR DIMM)~~

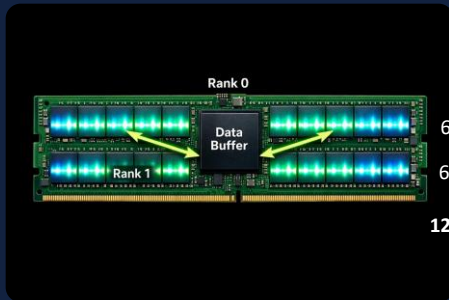
MRDIMM is an innovative DDR5 DIMM technology that delivers ~30% greater memory bandwidth over RDIMM with expected data transfer rate begin in 8800 MT/s, making it the fastest DDR5 DIMM available and supported in Xeon 6, 6+ and AMD Epyc 6th gen. CPU platforms for customers looking for the highest memory performance.

How It Works



Dual Rank RDIMM

Only 1 rank is active during a R/W cycle based on CS. Each rank operates independently to achieve rated speed.



Dual Rank MCR DIMM (MRDIMM)

Two ranks operate simultaneously to combine data lines using buffer chips located above edge fingers to achieve higher data rate.

MRDIMM Highlights

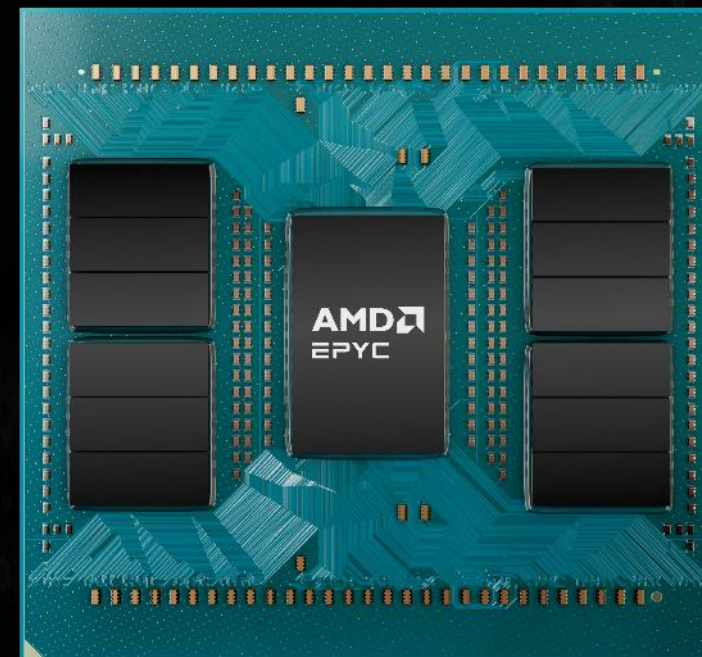
- Enables simultaneous operation of two ranks by utilizing the data buffer assembled onto the MRDIMM.
- By simultaneous operation of two ranks, MRDIMM allows transmission of 128 bytes of data to CPU at once, compared with 64 bytes fetched in conventional DRAM module.
- An increase in the amount of data sent to the CPU in each burst enables a data transfer rate greater than RDIMM.
- MRDIMM maintains the same DIMM form factor to support drop in compatibility.
- All reliability features of DDR5 are supported.



Introducing 5th Gen AMD EPYC™ Processors

Formerly codenamed “Turin”

World’s best CPU for cloud, enterprise & AI



TSMC 3/4nm

Up to **192 cores**
Up to **384 threads**

Up to **5GHz**

AVX512
full 512b data path

17% IPC Uplift

SP5 Platform
Compatible with “Genoa”



5th Gen AMD EPYC™ SoC

Soclet SP5 – the same as a Epyc 4th Gen (Genoa)

Blue text indicates significant update from “Zen 4”

Compute

- AMD “Zen5/Zen5c” x86 cores
 - “Zen5” up to 16 CCDs / 128 cores / 256 threads
 - “Zen5c” up to 12 CCDs / 192 cores / 384 threads
- 1MB L2/Core, Up to 32MB L3 per CCD

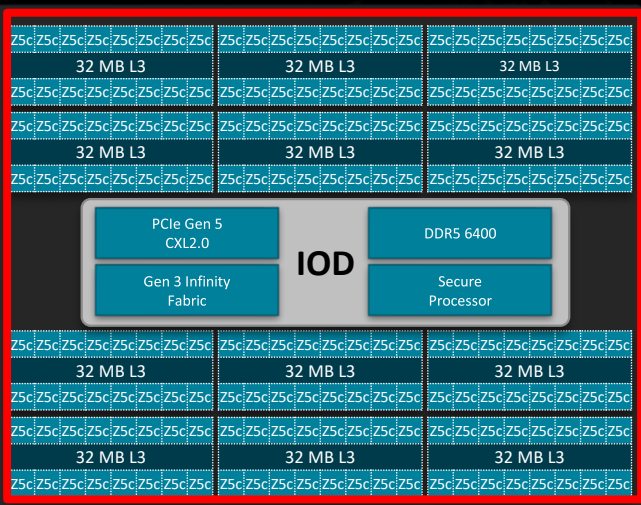
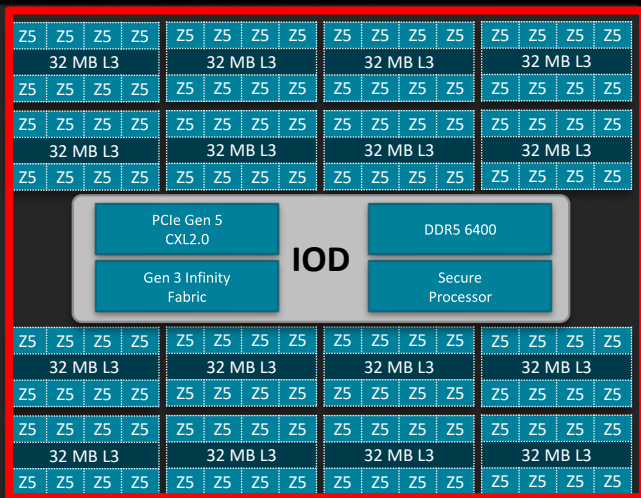
- ISA Updates: AVX-512 with 512b data path

- Infinity Fabric: 3rd-gen MCM (32+Gbps die-to-die)

- Dynamic PPR for x4 and x8 ECC RDIMMs
- BMC MCA Crash-Dump
- MCA over APML

SP5 Platform

- BIOS Update Required
- 2P and 1P Configurations
- Up to 4 links of 32Gbps Gen 3 Infinity Fabric™
- Compatible with “Genoa IRM” Groups up to 400W
- 500W IRM option for maximum performance
- Flexible topology options
- Server Controller Hub (USB, UART, SPI, I2C, etc.)



Memory

- 12 channel DDR5 with ECC up to 6400 MT/s
- Support for 2, 4, 6, 8, 10, 12 channel memory interleaving
- RDIMM, 3DS RDIMM
- Up to 2 DIMMs/channel capacity of 6TB/socket (256GB 3DS RDIMMs)

I/O

- 2P: up to 160 lanes of PCIe Gen5 with speeds up to 32Gbps/lane
 - up to 12 bonus PCIe Gen3 lanes
- 1P: 128 lanes of PCIe Gen5 with speeds up to 32Gbps/lane
 - up to 8 bonus PCIe Gen3 lanes
- PCIe bifurcations supported: x16, x8, x4, x2 and x1
- PCIe link encryption²
- CXL® 2.0, 4 x16 Capable “P” links; Type 3, Type 1², Type 2² PoC
- Up to 32 IO lanes for SATA
- SDCl (Smart Data Cache Injection)

Security¹

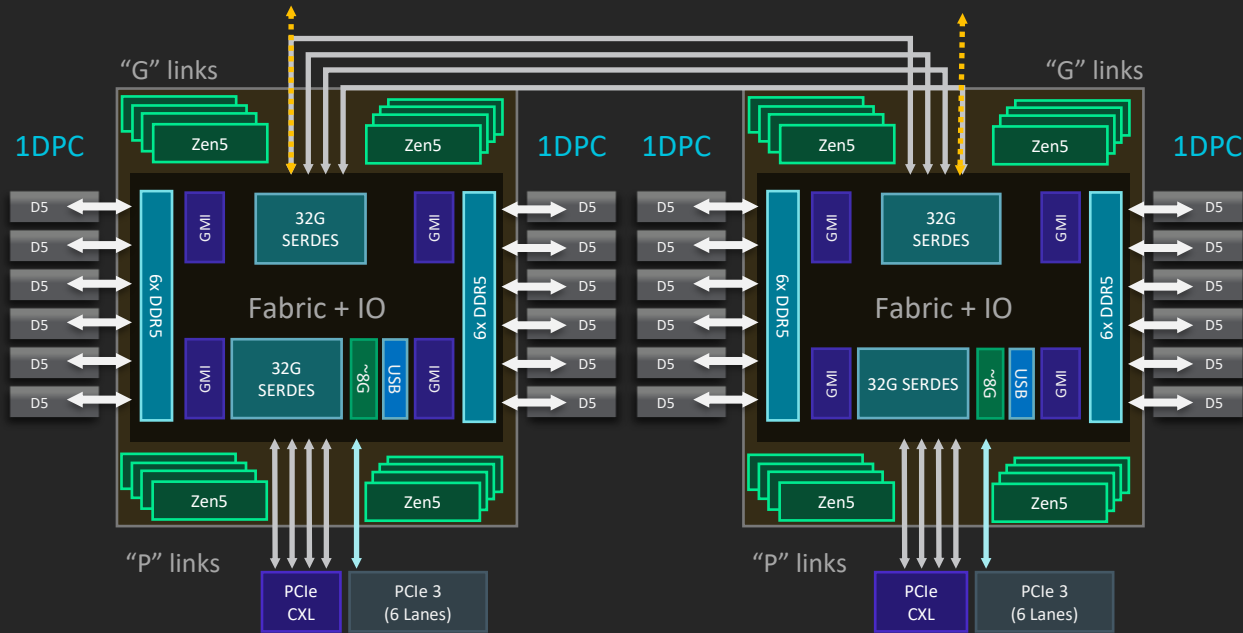
- Trusted IO
- Dedicated Security Subsystem with enhancements
- Hardware Root-of-Trust; Ciphertext-hiding capability

¹ - AMD Infinity Guard features vary by EPYC™ Processor generations and/or series. Infinity Guard security features must be enabled by server OEMs and/or Cloud Service Providers to operate. Check with your OEM or provider to confirm support of these features. Learn more about Infinity Guard at <https://www.amd.com/en/technologies/infinity-guard>. GD-183A

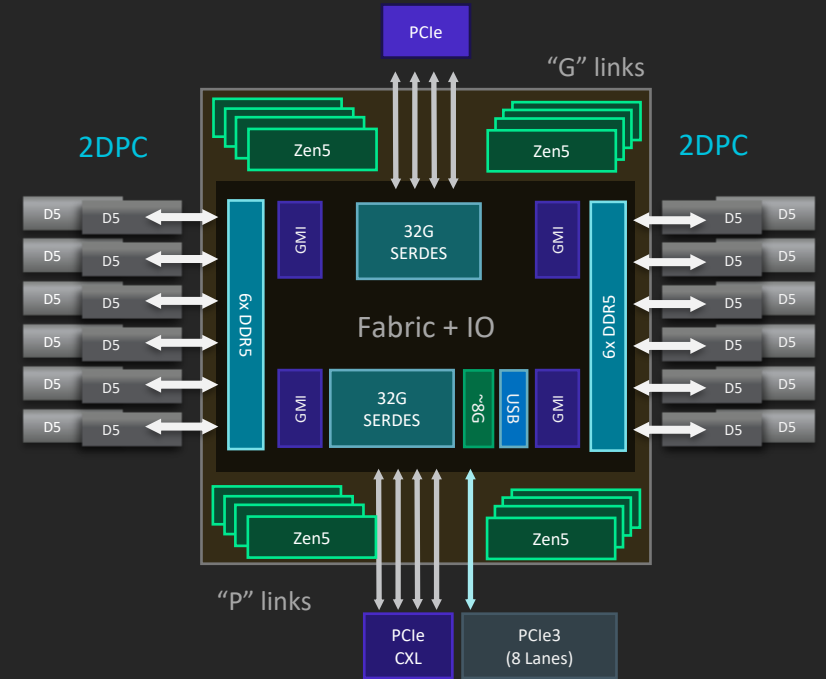
² - CXL Type 1&2 devices and PCIe link encryption support dependent upon ecosystem readiness
See endnotes: 9xx5-083A

5th Gen AMD EPYC™ SoC Platform Overview

2P Configuration



1P Configuration



**Strong upgrade to existing SP5
(4th Gen AMD EPYC™ CPU)
in the same platforms**

- 25% improvement in DRAM speed (4800 -> up to 6400) using JEDEC-standard (non-proprietary) DIMMs
- 1P PCIe® aggregate bandwidth improvement due to internal SOC topology changes
- Enhanced platform links option for 500W TDP capability



Turin Stack Reference: October 10, 2024

Product ID Tray	Model	CCD Type	Cores	Max. Boost Clock	Base Clock	L3 Cache	1kU Pricing	Default TDP	cTDP	Socket Count	DDR Max*
100-000000976	9965	Zen5c	192	3.7	2.25	384	\$ 14,813	500	450-500	2.0	6400
100-000001458	9845	Zen5c	160	3.7	2.1	320	\$ 13,564	390	320-400	2.0	6400
100-000000837	9825	Zen5c	144	3.7	2.2	384	\$ 13,006	390	320-400	2.0	6400
100-000001443	9755	Zen5	128	4.1	2.7	512	\$ 12,984	500	450-500	2.0	6400
100-000001460	9745	Zen5c	128	3.7	2.4	256	\$ 12,141	400	320-400	2.0	6400
100-000000674	9655	Zen5	96	4.5	2.6	384	\$ 11,852	400	320-400	2.0	6400
100-000001522	9655P	Zen5	96	4.5	2.6	384	\$ 10,811	400	320-400	1.0	6400
100-000001461	9645	Zen5c	96	3.7	2.3	256	\$ 11,048	320	320-400	2.0	6400
100-000001447	9565	Zen5	72	4.3	3.15	384	\$ 10,486	400	320-400	2.0	6400
100-000001554	9575F	Zen5	64	5	3.3	256	\$ 11,791	400	320-400	2.0	6400
100-000001142	9555	Zen5	64	4.4	3.2	256	\$ 9,826	360	320-400	2.0	6400
100-000001523	9555P	Zen5	64	4.4	3.2	256	\$ 7,983	360	320-400	1.0	6400
100-000001147	9535	Zen5	64	4.3	2.4	256	\$ 8,992	300	240-300	2.0	6400
100-000001143	9475F	Zen5	48	4.8	3.65	256	\$ 7,592	400	320-400	2.0	6400
100-000001542	9455	Zen5	48	4.4	3.15	256	\$ 5,412	300	240-300	2.0	6400
100-000001563	9455P	Zen5	48	4.4	3.15	256	\$ 4,819	300	240-300	1.0	6400
100-000001448	9365	Zen5	36	4.3	3.4	192	\$ 4,341	300	240-300	2.0	6400
100-000001197	9375F	Zen5	32	4.8	3.85	256	\$ 5,306	320	320-400	2.0	6400
100-000001148	9355	Zen5	32	4.4	3.55	256	\$ 3,694	280	240-300	2.0	6400
100-000001521	9355P	Zen5	32	4.4	3.55	256	\$ 2,998	280	240-300	1.0	6400
100-000001149	9335	Zen5	32	4.4	3	128	\$ 3,178	210	200-240	2.0	6400
100-000001144	9275F	Zen5	24	4.8	4.1	256	\$ 3,439	320	320-400	2.0	6400
100-000000694	9255	Zen5	24	4.3	3.25	128	\$ 2,495	200	200-240	2.0	6400
100-000001145	9175F	Zen5	16	5	4.2	512	\$ 4,256	320	320-400	2.0	6400
100-000001150	9135	Zen5	16	4.3	3.65	64	\$ 1,214	200	200-240	2.0	6400
100-000001552	9115	Zen5	16	4.1	2.6	64	\$ 726	125	120-155	2.0	6400
100-000001553	9015	Zen5	8	4.1	3.6	64	\$ 527	125	120-155	2.0	6400

*EPYC 9005 series processors support DDR5-6400 for targeted customers and configurations. See endnote 9xx5-083
As of 10/10/2024.


Compare of SPEC (Intel/AMD)

Intel Xeon 2x 6767P (Total 128-core)


64-core, 2,4GHz, 336 MB L3 cache


AMD Epyc 9555 (Total 128-core)

64-core, 3,2GHz, 256 MB L3 cache

 SPEC CPU® 2017 Integer Speed Result <small>Copyright 2017-2025 Standard Performance Evaluation Corporation</small>	
Dell Inc.	SPECSpeed®2017_int_base = 14.3
PowerEdge R670 (Intel Xeon 6767P)	SPECSpeed®2017_int_peak = 14.4
CPU2017 License: 6573 Test Sponsor: Dell Inc. Tested by: Dell Inc.	Test Date: Mar-2025 Hardware Availability: Mar-2025 Software Availability: Jun-2024

 SPEC CPU® 2017 Integer Speed Result <small>Copyright 2017-2025 Standard Performance Evaluation Corporation</small>	
ASUSTeK Computer Inc.	SPECSpeed®2017_int_base = 19.4
ASUS RS720A-E13-RS8U (3.20 GHz, AMD EPYC 9555)	SPECSpeed®2017_int_peak = 19.7
CPU2017 License: 9016 Test Sponsor: ASUSTeK Computer Inc. Tested by: ASUSTeK Computer Inc.	Test Date: Jul-2025 Hardware Availability: Mar-2025 Software Availability: Oct-2024

 SPEC CPU® 2017 Floating Point Rate Result <small>Copyright 2017-2025 Standard Performance Evaluation Corporation</small>	
Dell Inc.	SPECrate®2017_fp_base = 1450
PowerEdge R670 (Intel Xeon 6767P)	SPECrate®2017_fp_peak = 1500
CPU2017 License: 6573 Test Sponsor: Dell Inc. Tested by: Dell Inc.	Test Date: Mar-2025 Hardware Availability: Mar-2025 Software Availability: Jun-2024

 SPEC CPU® 2017 Floating Point Rate Result <small>Copyright 2017-2025 Standard Performance Evaluation Corporation</small>	
ASUSTeK Computer Inc.	SPECrate®2017_fp_base = 1820
ASUS RS720A-E13-RS8U (3.20 GHz, AMD EPYC 9555)	SPECrate®2017_fp_peak = 1970
CPU2017 License: 9016 Test Sponsor: ASUSTeK Computer Inc. Tested by: ASUSTeK Computer Inc.	Test Date: Jul-2025 Hardware Availability: Mar-2025 Software Availability: Oct-2024

Intel vs AMD — Server Processor Comparison

INTEL

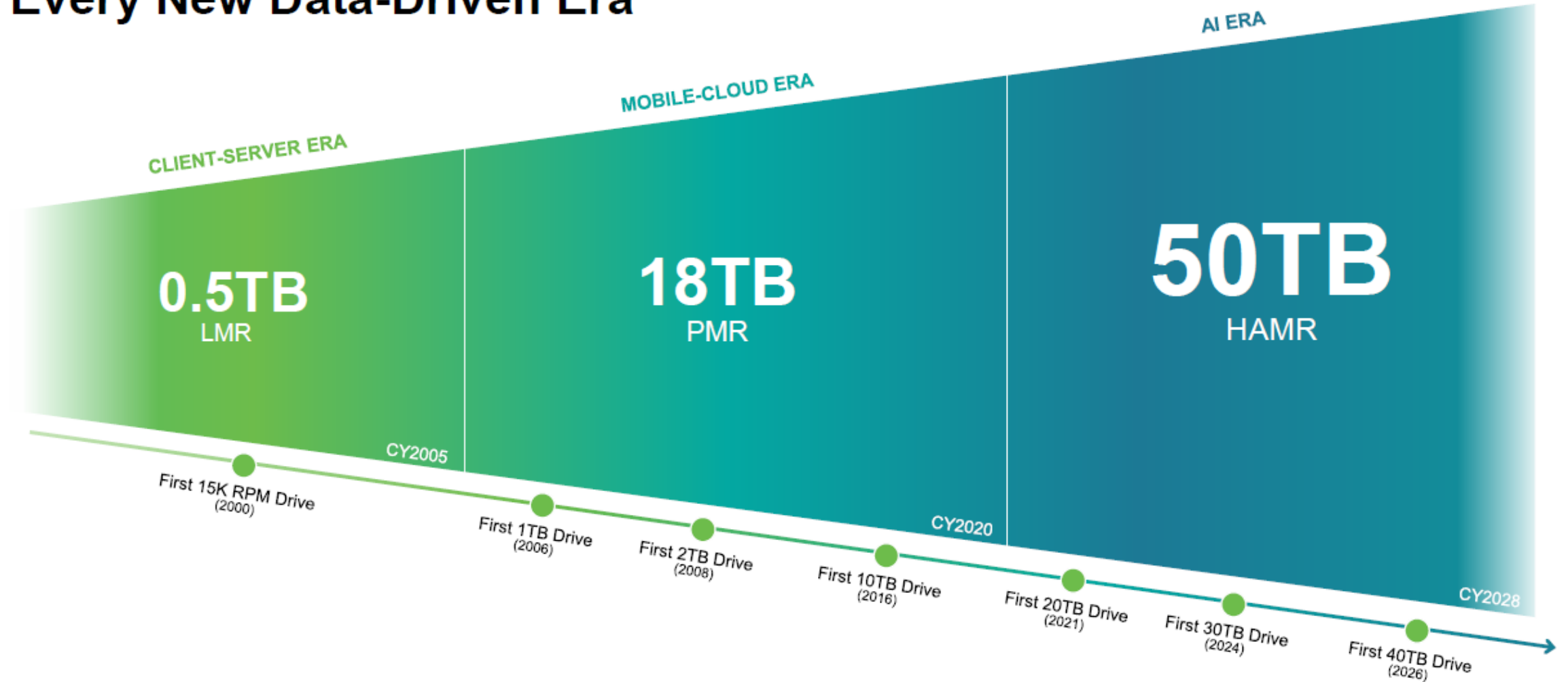
AMD

Feature	Intel Xeon 6	Intel Xeon 6+	AMD EPYC Turin (5th Gen)	AMD EPYC Venice (6th Gen)
Codename	Granite Rapids / Sierra Forest	Clearwater Forest	Turin / Turin Dense	Venice
Core Architecture	Redwood Cove (P) / Crestmont (E)	Darkmont (E-cores)	Zen 5 (P) / Zen 5c (Dense)	Zen 6 (P) / Zen 6c (Dense)
Process Node	Intel 3 (3nm-class)	Intel 18A (1.8nm)	TSMC 3nm (CCD) + 4nm (IOD)	TSMC 2nm (CCD) + 4nm (IOD)
Max Core Count	Up to 128 P / 288 E	Up to 288 E-cores	Up to 96 Zen 5 / 192 Zen 5c	Up to 96 Zen 6 / 256 Zen 6c
Max Thread Count	256 (P) / 288 (E)	288 threads	192 (Zen 5) / 384 (Zen 5c)	192 (Zen 6) / 512 (Zen 6c)
Max L3 Cache	Up to 504 MB	High-density 3D Fabric	Up to 512 MB	Up to 1 TB (Multi-CCD)
Memory Channels	8-channel / 12-channel DDR5	12-channel DDR5	12-channel DDR5	16-channel DDR5
Memory Speed	Up to 6400 MT/s (MCR to 8800)	Up to DDR5-8000	Up to 6400 MT/s	Up to 8000 (MRDIMM to 12,800)
PCIe / CXL	PCIe 5.0 / CXL 2.0	PCIe 5.0 / CXL 2.0	PCIe 5.0 / CXL 2.0	PCIe 6.0 / CXL 3.0
Max TDP	Up to 500W	Optimized for Telco/Cloud	Up to 400W (configurable)	Up to 600W (SP7)
Socket	LGA 4710 / LGA 7529	LGA 7529 (Compatible)	SP5	SP7 / SP8
Availability	Available Now	Launched Q1 2026	Available Now	Expected Mid-to-Late 2026



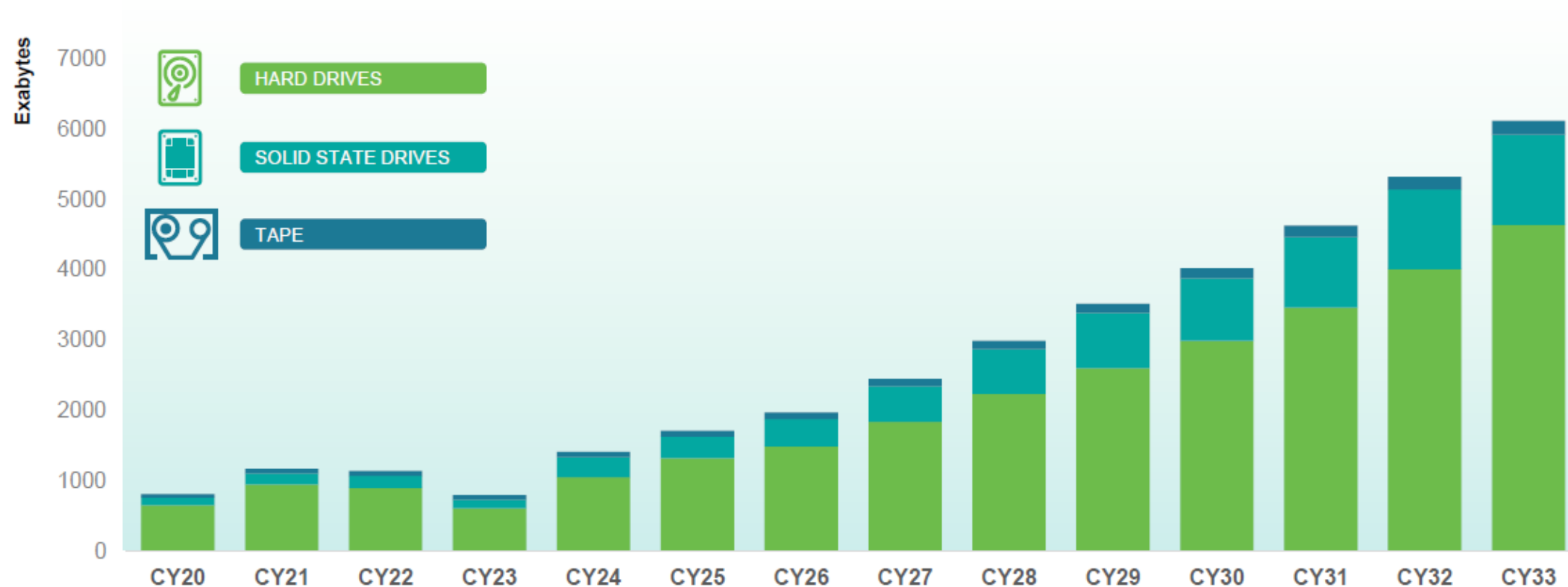
AI is data. Data is storage.
Storage is **Seagate!**

Seagate's Storage Innovation Enabling Every New Data-Driven Era

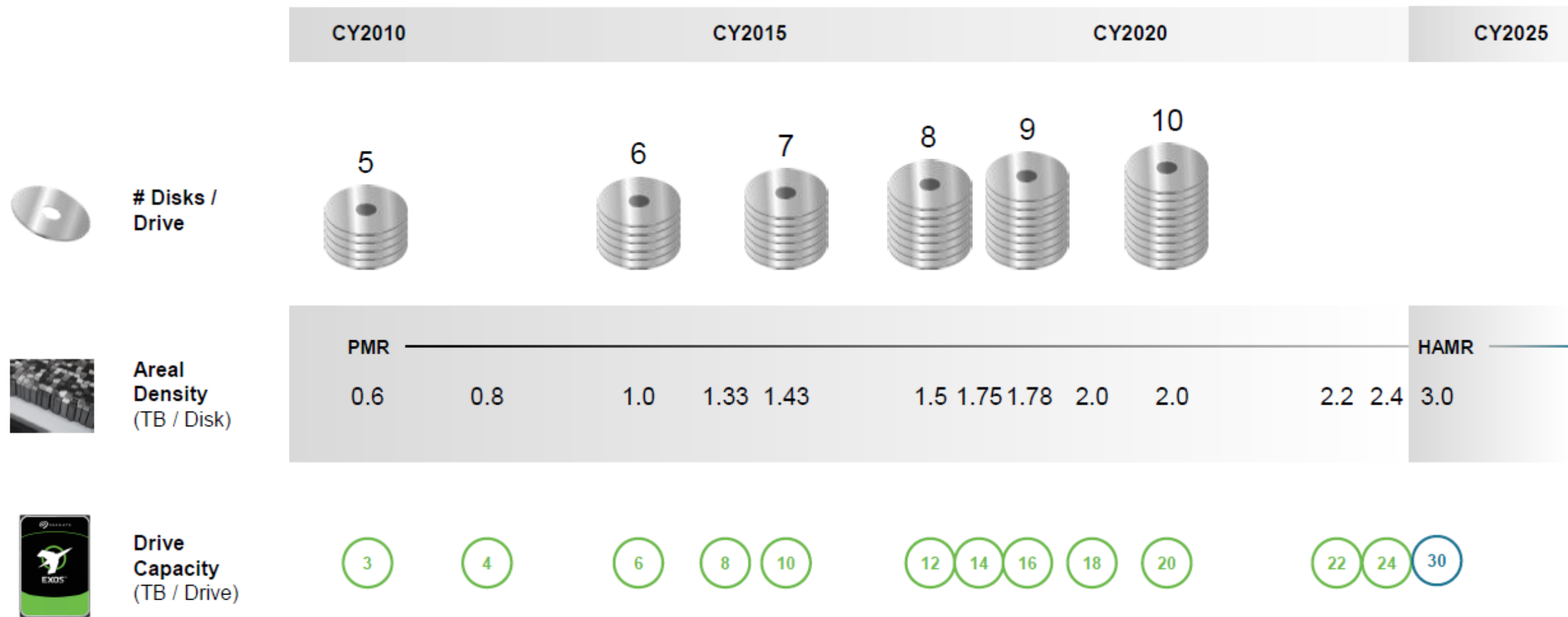


ENTERPRISE SCALE

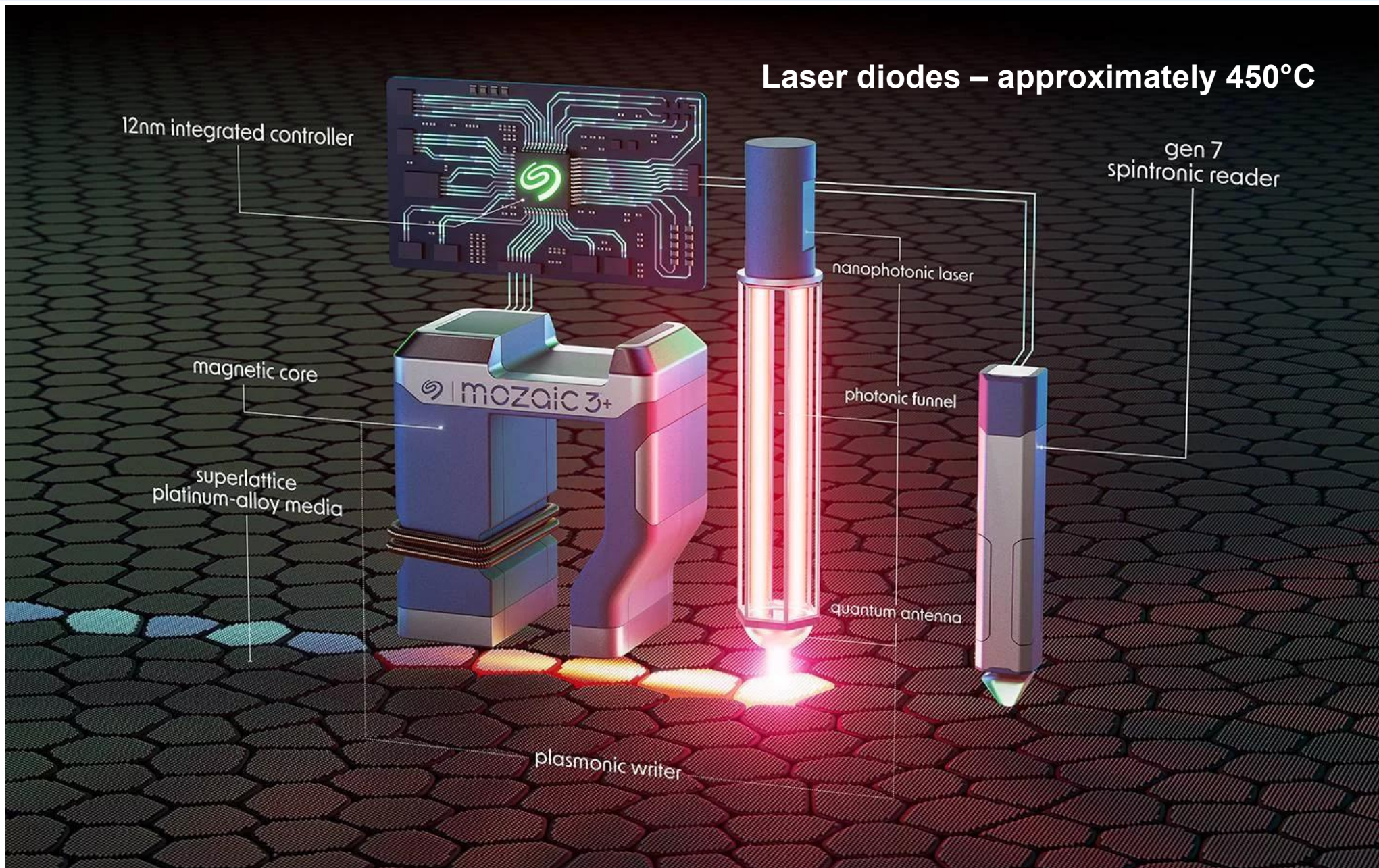
The ecosystem demands diverse memory and storage solutions to support evolving AI architectures



Hard Drive Capacity Scaling is Reaching Limits With PMR Technology



Laser diodes – approximately 450°C



Exos

4 TB+ per disk. Up to 44 TB per drive.

With category-defining areal density of 4 TB+ per disk, Mozaic unlocks hard drive capacities up to 44 TB while preserving a highly efficient 10-disk architecture — allowing data centres to increase storage capacity without expanding physical footprint.





Market & Business Highlights

- DDR4 server grade DRAM supply is extremely tight. Any remaining server-grade output will be prioritized by the semiconductor suppliers to support large CSP's and data center customers, which have the highest margins. DDR4 server-grade DRAM pricing has doubled over the last 2 months.
- DDR4 PC supply has stabilized, but mainly for 8Gbit x8 chips. 16Gbit wafer output is prioritized for DDR4 server demand.
 - Kingston's DDR4 PC-grade supply is stable. We expect consistent supply through 2025 and into 2026.
- DDR5 server demand surged as CSPs and DCs continue the "AI arms race." All DRAM semiconductor suppliers are citing severe shortages for at least the next 3 quarters.
- DRAM production output now prioritizes HBM, LPDDR5X, and DDR5 server grade, significantly reducing PC grade.
- Kingston still maintains stable DDR5 supply based on our LTA agreements, but we expect supply to continue to tighten and costs to be pushed up by the suppliers.



DDR5



DDR5 SPECIFICATIONS

Form Factors

- 288-pin DIMM
- 262-pin SODIMM

Performance (in MT/s)

4400 / **4800** / 5200 / 5600 / 6000 / 6400

Power

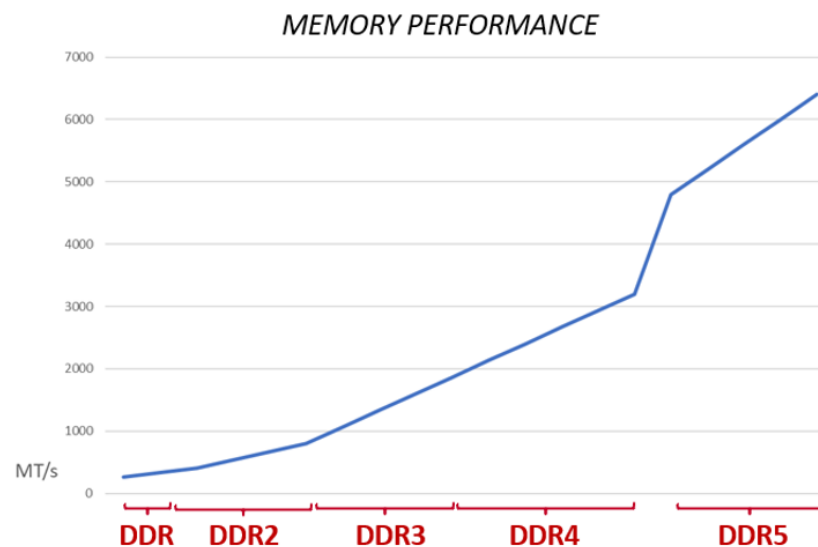
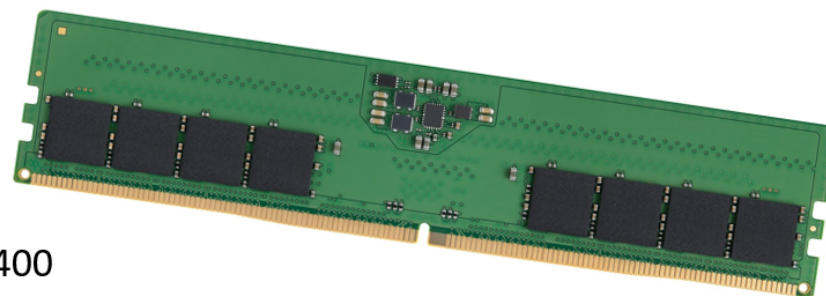
- 1.1 V
- 12V for Hybrid DIMM (3-pins)

DRAM Densities / DIMM Capacities

- 8Gb, **16Gb**, 24Gb, 32Gb (x4, x8, x16)
- 8GB, 12GB, 16GB, 24GB, 32GB, 48GB, 64GB, 96GB, 128GB, 192GB, 256GB, 384GB, 512GB

Module Types

- Registered DIMM
- Load Reduced DIMM
- ECC Unbuffered DIMM / SODIMM
- Non-ECC Unbuffered DIMM / SODIMM

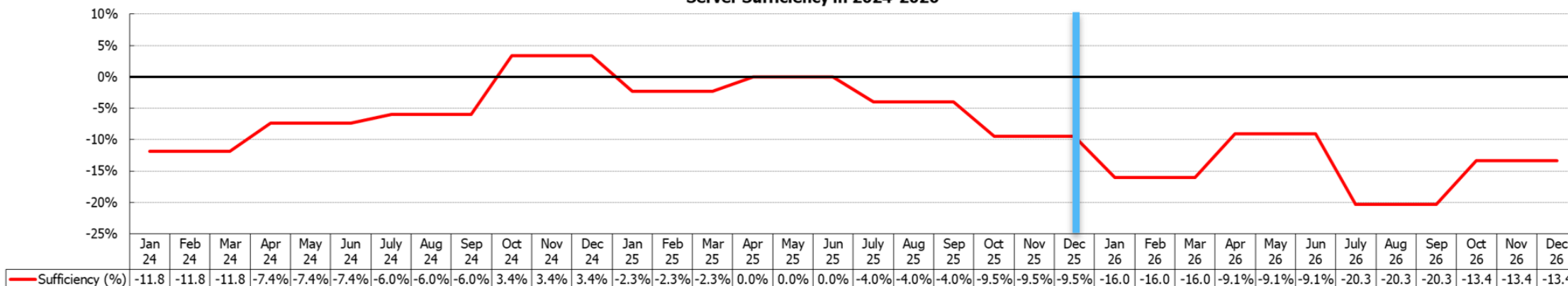


JEDEC Industry Standard Specifications

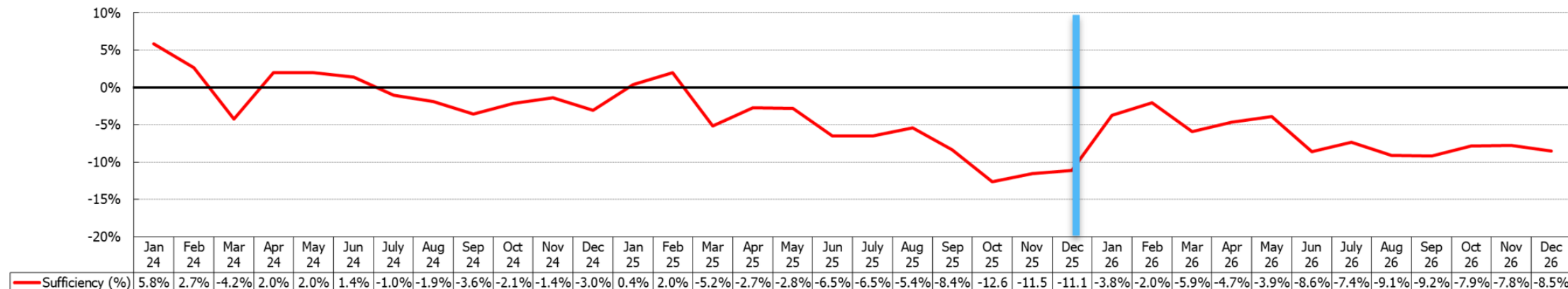
Description	DDR5	
Data Rates (Speed in MT/s)	4000, 4400, 4800, 5200, 5600, 6000, 6400 MT/s	
Monolithic DRAM Densities (Gbit)	8Gb, 16Gb, 24Gb, 32Gb, 48Gb, 64Gb	
Package Type and Ballout (x4, x8 / x16)	BGA, 3DS TSV (78, 82 / 102)	
Interface	Voltage (V_{DD} / V_{DDQ} / V_{FF})	1.1 / 1.1 / 1.8 V
	Internal V_{REF}	V_{REFDQ} , V_{REFCA} , V_{REFCS}
	Command/Address	POD (Pseudo Open Drain)
	Equalization	DFE (Dynamic Feedback Equalization)
	Burst Length	BL16 / BC8 / BL32 (optional)
Core Architecture	Number of Banks	32 Banks (8 Bank Groups) 8 BG x 4 banks (16-64Gb x4/x8) 8 BG x 2 banks (8Gb x4/x8) 16 Banks (4 Bank Groups) 4 BG x 4 banks (16-64Gb x16) 4 BG x 2 banks (8Gb x16)
	Page Size (x4 / x8 / x16)	1KB / 1KB / 2KB
	Prefetch	16n
	DCA (Duty Cycle Adjustment)	DQS and DQ
	Internal DQS Delay Monitoring	DQS interval oscillator
	ODECC (On-die ECC)	128b+8b SEC error check and scrub
	CRC (Cyclic Redundancy Check)	Read/Write
	ODT (On-die Termination)	DQ, DQS, DM, CA bus
	MIR ("Mirror" pin)	Yes
	Bus Inversion	Command/address inversion (CAI)
CA Training, CS Training	CA training, CS training	
Write Leveling Training Modes	Improved	
Read Training Patterns	Dedicated MRs for user-defined serial, clock, and LFSR - generated training patterns	
Mode registers	Up to 256 x 8 bits	
PRECHARGE Commands	All bank, per bank, and same bank	
REFRESH Commands	All bank and same bank	
Loopback Mode	Yes	

Global Supply Sufficiency

Server Sufficiency in 2024-2026



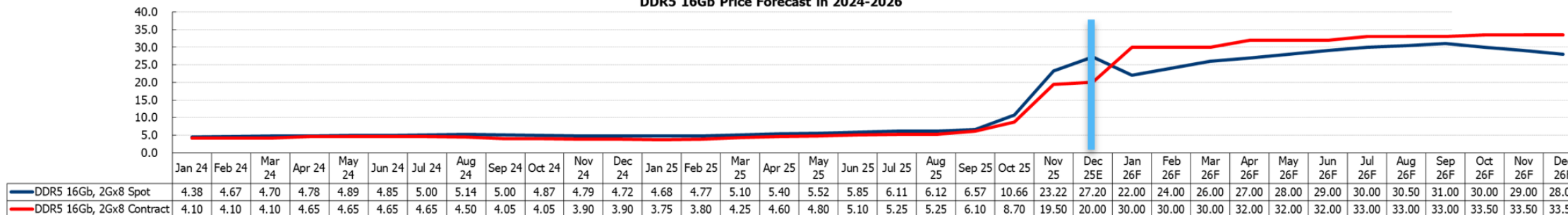
PC Sufficiency in 2024-2026



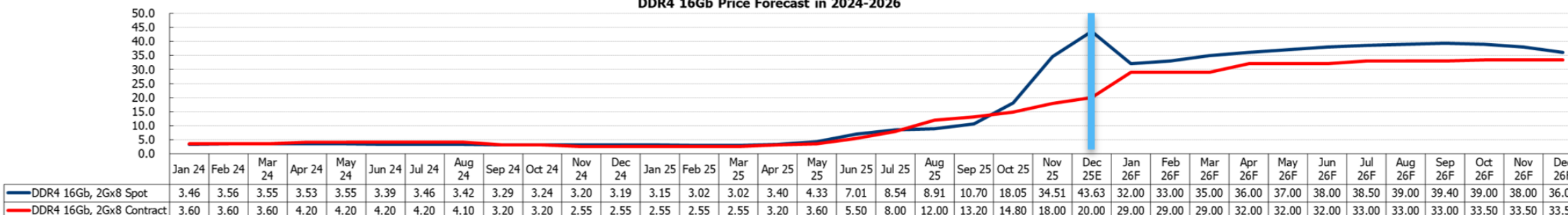
Price Forecast



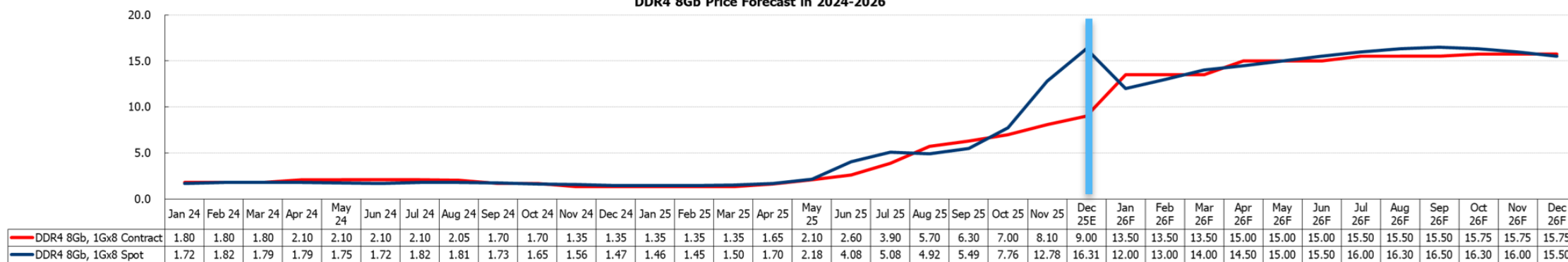
DDR5 16Gb Price Forecast in 2024-2026



DDR4 16Gb Price Forecast in 2024-2026



DDR4 8Gb Price Forecast in 2024-2026



NVMe SSD DC3000ME (Gen 5)

3,84TB, 7,68 TB, 15,36 TB, 30,72 TB

Specifications

Form factor	U.2, 2.5" x 15mm
Interface	PCIe NVMe Gen5 x4 (backward compatible with Gen4)
Capacities ¹	3.84TB, 7.68TB, 15.36TB, 30.72TB
NAND	3D eTLC
Sequential read/write ²	3.84TB - 14,000MB/s / 5,800MB/s 7.68TB - 14,000MB/s / 10,000MB/s 15.36TB - 14,000MB/s / 9,700MB/s 30.72TB - 14,000MB/s / 9,700MB/s
4k random read/write (IOPS) ²	3.84TB - 2,700,000 / 300,000 7.68TB - 2,800,000 / 500,000 15.36TB - 2,700,000 / 400,000 30.72TB - 2,600,000 / 350,000
Latency quality of service (QoS) ^{2, 3, 4}	3.84TB-15.36TB 99% - Read/Write: <70 µs / < 10 µs 30.72TB 99% - Read/Write: <175 µs / < 12 µs
Static and dynamic wear levelling	Yes
Power loss protection (power caps)	Yes
Encryption	Yes - TCG Opal 2.0, AES 256-bit encryption
Namespace management support	Yes - 128 namespaces supported
Enterprise diagnostics	Telemetry, media wear, temperature, health, etc.
Endurance (TBW/DWPD) ⁵	3.84TB - 7,008TB, 1DWPD (5 years) 7.68TB - 14,016TB, 1DWPD (5 years) 15.36TB - 28,032TB, 1DWPD (5 years) 30.72TB - 56,064TB, 1DWPD (5 years)





Thank you

VÁŠ PRŮVODCE
SVĚTEM **IT**

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